TMP75C-Q1 1.8Vデジタル温度センサ、2線式インターフェイスおよびアラート付き

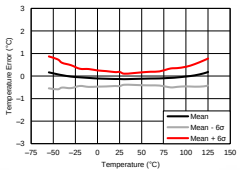
1 特長

- 車載アプリケーションに対応
- 下記内容でAEC-Q100認定済み：
  - デバイス温度グレード1: 動作時周囲温度範囲 –40°C～125°C
  - デバイスHBM ESD分類レベル2
  - デバイスCDM ESD分類レベルC5
- NCT75およびADT75に対する低電圧の代替品
- 2線式シリアル・インターフェイス付きのデジタル出力
- ピンによりプログラム可能な8つまでのバス・アドレス
- 過熱通知用ALERTピン、トリップ値のプログラム可能
- シャットダウン・モードによるバッテリ電力削減
- ワンショット変換モード
- 動作温度範囲: -40℃～125℃
- 動作電源電圧範囲: 1.4V～3.6V
- 静止電流:
  アクティブ時15µA (標準値)、シャットダウン時0.3µA (標準値)
- 精度:
  - 0℃～+70℃について±0.25℃ (標準値)
  - -20℃～+85℃について±0.5℃ (標準値)
  - -40℃～+125℃について±1℃ (標準値)
- 分解能: 12ビット(0.0625℃)
- パッケージ: SOIC-8およびVSSOP-8

2 アプリケーション

- サーバーおよびコンピュータの熱管理
- テレコミュニケーション機器
- オフィス機器、セットトップ・ボックス、サーモスタット制御
- ビデオゲーム・コンソール
- 電源およびバッテリの熱保護
- 環境監視とHVAC
- 電気モータ・ドライバの熱保護

温度精度(誤差)と周囲温度との関係



3 概要

TMP75C-Q1は統合されたデジタル温度センサで、12ビットのアナログ/デジタル・コンバータ(ADC)を持ち、1.8Vの電源で動作し、NCT75およびADT75とピンおよびレジスタ互換です。このデバイスはSOIC-8およびVSSOP-8パッケージで利用可能で、外付け部品なしに温度を感知できます。TMP75C-Q1は0.0625℃の分解能で温度を読み取りでき、-40℃～+125℃の温度範囲について動作が規定されています。

TMP75C-Q1にはSMBusおよび2線式インターフェイスとの互換性があり、8つまでのデバイスを同じバスに接続でき、SMBusの過熱アラート機能を使用できます。プログラム可能な温度制限とALERTピンにより、このセンサはスタンドアロンのサーモスタット、または電源スロットルやシステム・シャットダウン用の過熱アラームとして動作できます。

工場で較正済みの温度精度と、ノイズ耐性のあるデジタル・インターフェイスにより、TMP75C-Q1は他のセンサーや電子部品の温度補償に適切なソリューションで、システムレベルでの追加較正や、基板の複雑なレイアウトを必要とせず、分散温度センシングが可能です。

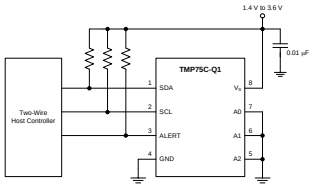
TMP75C-Q1は各種のコンシューマ、コンピュータ、通信、産業用、環境用アプリケーションの熱管理および保護に理想的です。

製品情報(1)

型番	パッケージ	本体サイズ(公称)
TMP75C-Q1	SOIC (8)	4.90mm×3.90mm
	VSSOP (8)	3.00mm×3.00mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にあるパッケージ・オプションについての付録を参照してください。

概略回路図



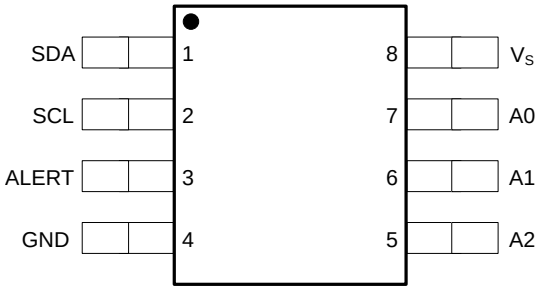
目次

4 改訂履歴

日付	改訂内容	注
2016年11月	*	初版

5 Pin Configuration and Functions

D and DGK Packages
8-Pin SOIC and VSSOP
Top View



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
A0	7	I	Address select. Connect to GND or V_S.
A1	6	I	Address select. Connect to GND or V_S.
A2	5	I	Address select. Connect to GND or V_S.
ALERT	3	O	Overtemperature alert. Open-drain output; requires a pull-up resistor.
GND	4	—	Ground.
SCL	2	I	Serial clock.
SDA	1	I/O	Serial data. Open-drain output; requires a pull-up resistor.
V_S	8	I	Supply voltage, 1.4 V to 3.6 V.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
Supply voltage, V_S			4	V
Input voltage	SDA, SCL, ALERT, A2, A1	–0.3	4	V
	A0	–0.3	(V_S) + 0.3	V
Sink current	SDA, ALERT		10	mA
Operating junction temperature		–40	150	°C
Storage temperature, T_{stg}		–60	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 (1)	±2000	V
		Charged-device model (CDM), per AEC Q100-011	±1000	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
Supply voltage	1.4	1.8	3.6	V
Operating free-air temperature, T_A	–40		125	°C

6.4 Thermal Information

THERMAL METRIC (1)		TMP75C-Q1		UNIT
		D (SOIC)	DGK (VSSOP)	
		8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	125.4	188.1	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	71.5	79.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	65.8	109.6	°C/W
ψ_{JT}	Junction-to-top characterization parameter	21.1	15.3	°C/W
ψ_{JB}	Junction-to-board characterization parameter	65.3	108	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.

6.5 Electrical Characteristics

At T_A = –40°C to +125°C and V_S = +1.4 V to +3.6 V, unless otherwise noted. Typical values at T_A = 25°C and V_S = +1.8 V.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
TEMPERATURE INPUT						
	Temperature range		–40		125	°C
	Temperature resolution			0.0625		°C
	Temperature accuracy (error)	0°C to +70°C		±0.25	±1	°C
		–20°C to +85°C		±0.5	±2	
		–40°C to +125°C		±1	±3	
DIGITAL INPUT/OUTPUT						
V_{IH}	High-level input voltage		0.7(V_S)		V_S	V
V_{IL}	Low-level input voltage		-0.3		0.3(V_S)	V
I_{IN}	Input current	0 V < V_{IN} < (V_S) + 0.3 V			1	µA
V_{OL}	Low-level output voltage	V_S ≥ 2 V, I_{OUT} = 3 mA			0.4	V
		V_S < 2 V, I_{OUT} = 3 mA			0.2(V_S)	
	ADC resolution			12		Bit
	Conversion time	One-shot mode	20	27	35	ms
	Update Rate			80		ms
	Bus timeout time		16	22	29	ms
POWER SUPPLY						
	Operating supply range		1.4		3.6	V
I_Q	Quiescent current	Serial bus inactive		15	37	µA
		Serial bus active, SCL frequency = 400 kHz		25		
		Serial bus active, SCL frequency = 3.4 MHz		95		
I_{SD}	Shutdown current	Serial bus inactive		0.3	8	µA
		Serial bus active, SCL frequency = 400 kHz		10		
		Serial bus active, SCL frequency = 3.4 MHz		80		

6.6 Typical Characteristics

At T_A = 25°C and V_S = +1.8 V (unless otherwise noted).

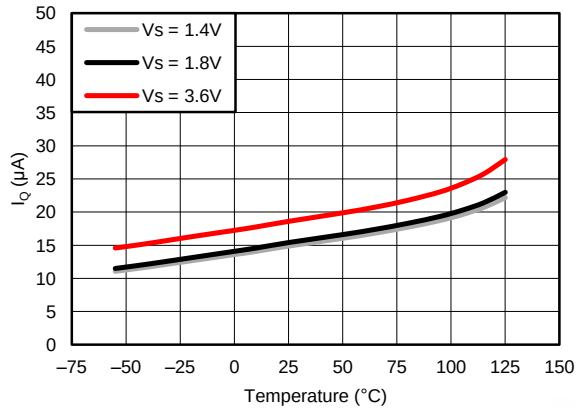


Figure 1. Quiescent Current vs Temperature

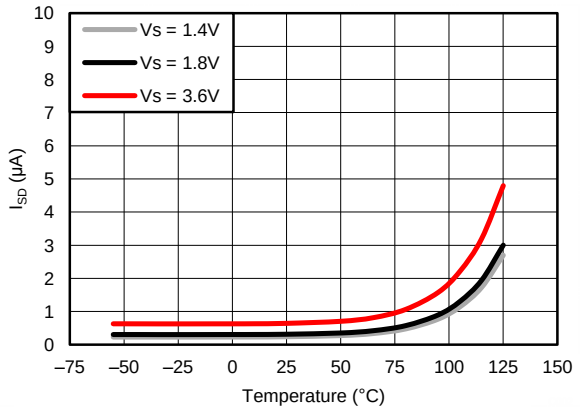


Figure 2. Shutdown Current vs Temperature

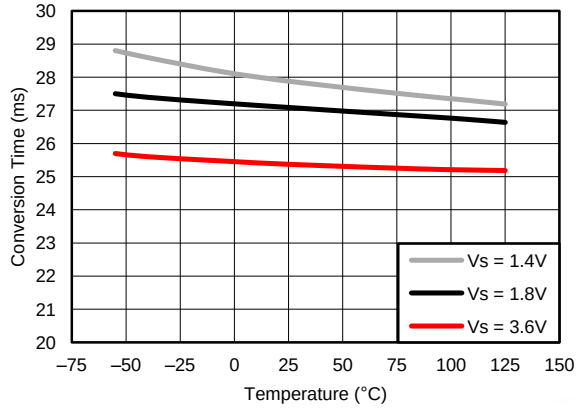


Figure 3. Conversion Time vs Temperature

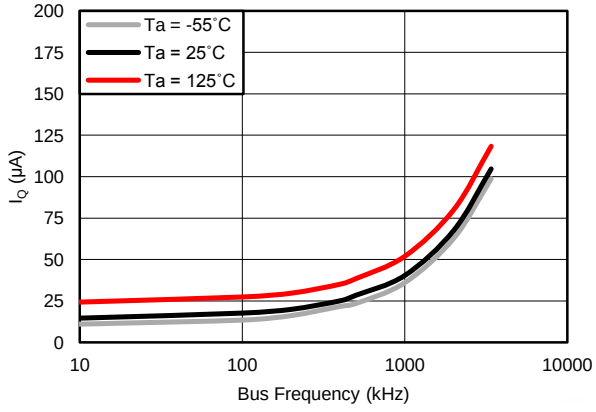


Figure 4. Quiescent Current vs Bus Frequency

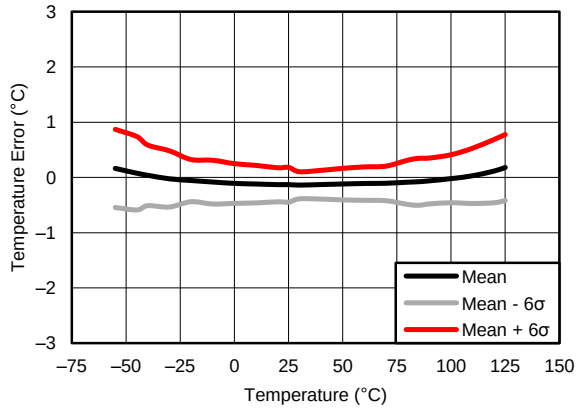


Figure 5. Temperature Error vs Temperature

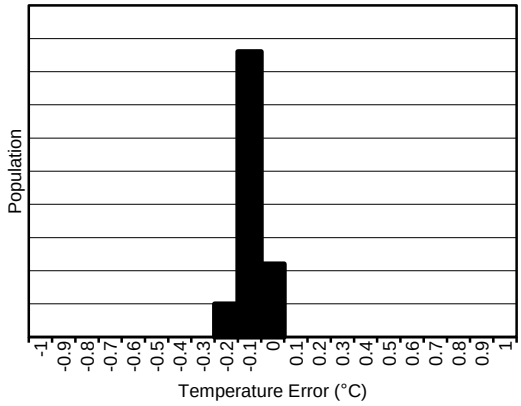


Figure 6. Temperature Error at 25°C

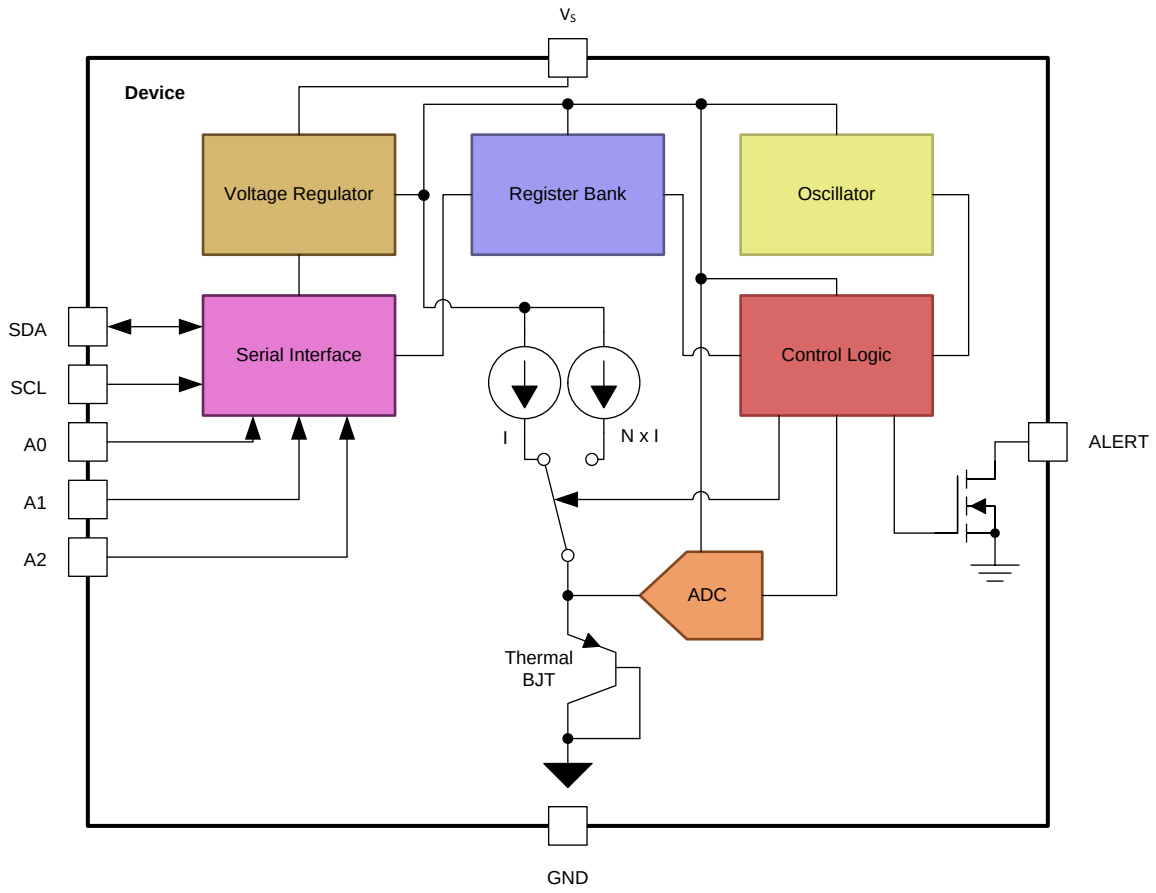
7 Detailed Description

7.1 Overview

The TMP75C-Q1 is a digital temperature sensor optimal for thermal management and thermal protection applications. The TMP75C-Q1 is two-wire and SMBus interface compatible, and is specified over a temperature range of –40°C to +125°C.

The temperature sensing device for the TMP75C-Q1 is the chip itself. A bipolar junction transistor (BJT) inside the chip is used in a band-gap configuration to produce a voltage proportional to the chip temperature. The voltage is digitized and converted to a 12-bit temperature result in degrees Celsius, with resolution of 0.0625°C. The package leads provide the primary thermal path because of the lower thermal resistance of the metal. Thus, the temperature result is equivalent to the local temperature of the printed circuit board (PCB) where the sensor is mounted.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Digital Temperature Output

The 12-bit digital output from each temperature measurement conversion is stored in the read-only temperature register. Two bytes must be read to obtain the data, as shown in Figure 14. Note that byte 1 is the most significant byte, followed by byte 2, the least significant byte. The temperature result is left-justified with the 12 most significant bits used to indicate the temperature. There is no need to read the second byte if resolution below 1°C is not required. Table 1 summarizes the temperature data format. One LSB equals 0.0625°C. Negative numbers are represented in binary twos complement format.

Table 1. Temperature Data Format(1)

TEMPERATURE (°C)	DIGITAL OUTPUT	
	BINARY	HEX
128	0111 1111 1111	7FF
127.9375	0111 1111 1111	7FF
100	0110 0100 0000	640
80	0101 0000 0000	500
75	0100 1011 0000	4B0
50	0011 0010 0000	320
25	0001 1001 0000	190
0.25	0000 0000 0100	004
0	0000 0000 0000	000
–0.25	1111 1111 1100	FFC
–25	1110 0111 0000	E70
–40	1101 1000 0000	D80

(1) The temperature sensor resolution is 0.0625°C/LSB.

Table 1 does not supply a full list of all temperatures. Use the following rules to obtain the digital data format for a given temperature, and vice versa.

To convert positive temperatures to a digital data format:

Divide the temperature by the resolution. Then, convert the result to binary code with a 12-bit, left-justified format, and MSB = 0 to denote a positive sign.

Example: (+50°C) / (0.0625°C / LSB) = 800 = 320h = 0011 0010 0000

To convert a positive digital data format to temperature:

Convert the 12-bit, left-justified binary temperature result, with the MSB = 0 to denote a positive sign, to a decimal number. Then, multiply the decimal number by the resolution to obtain the positive temperature.

Example: 0011 0010 0000 = 320h = 800 × (0.0625°C / LSB) = +50°C

To convert negative temperatures to a digital data format:

Divide the absolute value of the temperature by the resolution, and convert the result to binary code with a 12-bit, left-justified format. Then, generate the twos complement of the result by complementing the binary number and adding one. Denote a negative number with MSB = 1.

Example: (|–25°C|) / (0.0625°C / LSB) = 400 = 190h = 0001 1001 0000

Two's complement format: 1110 0110 1111 + 1 = 1110 0111 0000

To convert a negative digital data format to temperature:

Generate the twos compliment of the 12-bit, left-justified binary number of the temperature result (with MSB = 1, denoting negative temperature result) by complementing the binary number and adding one. Convert to decimal number and multiply by the resolution to get the absolute temperature, then multiply by –1 for the negative sign.

Example: 1110 0111 0000 has twos complement of 0001 1001 0000 = 0001 1000 1111 + 1

Convert to temperature: 0001 1001 0000 = 190h = 400; 400 × (0.0625°C / LSB) = 25°C = (|–25°C|); (|–25°C|) × (–1) = –25°C

7.3.2 Temperature Limits and Alert

The temperature limits are stored in the T_{LOW} and T_{HIGH} registers (Table 7 and Table 8) in the same format as the temperature result, and their values are compared to the temperature result on every conversion. The outcome of the comparison drives the behavior of the ALERT pin, which can operate as a comparator output or an interrupt, and is set by the TM bit in the Configuration register (Table 6).

In comparator mode (TM = 0, default), the ALERT pin becomes active when the temperature is equal to or exceeds the value in T_{HIGH} (fault conditions) for a consecutive number of conversions as set by the FQ bits of the configuration register. ALERT clears when the temperature falls below T_{LOW} for the same consecutive number of conversions. The difference between the two limits acts as a hysteresis on the comparator output, and a fault counter prevents false alerts as a result of environmental noise.

In interrupt mode (TM = 1), the ALERT pin becomes active when the temperature equals or exceeds the value in T_{HIGH} for a consecutive number of fault conditions. The ALERT pin remains active until a read operation of any register occurs. After the ALERT pin is cleared, this pin becomes active again only when temperature falls below T_{LOW} for a consecutive number of fault conditions, and remains active until cleared by a read operation of any register. The cycle repeats with the ALERT pin becoming active when the temperature equals or exceeds T_{HIGH}, and so on. The ALERT pin is cleared also when the device is placed in shutdown mode (see Shutdown Mode for shutdown mode description). This action also clears the fault counter memory.

The active state of the ALERT pin is set by the POL bit in the configuration register. When POL = 0 (default), the ALERT pin is active low. When POL = 1, the ALERT pin is active high. The operation of the ALERT pin in the various modes is illustrated in Figure 7.

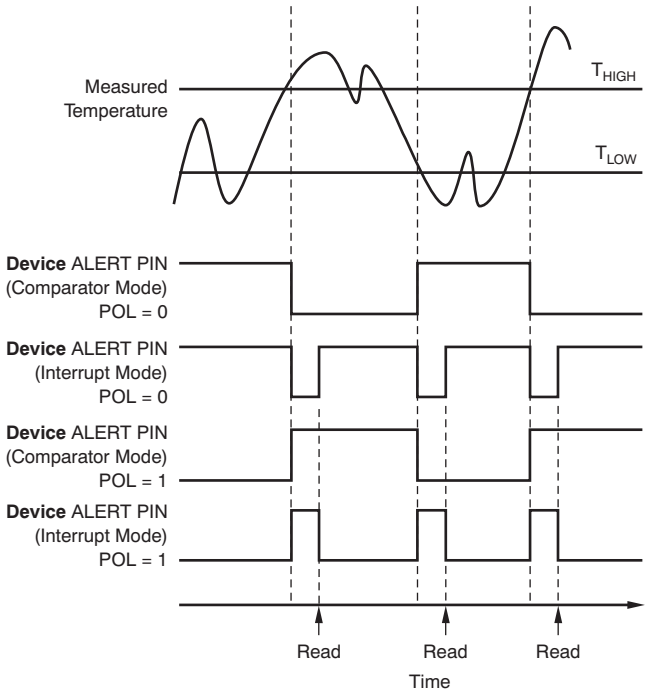


Figure 7. ALERT Pin Modes of Operation

7.3.3 Serial Interface

The TMP75C-Q1 operates as a slave device only on the two-wire bus and SMBus. Connections to the bus are made using the open-drain I/O lines, SDA and SCL. The SDA and SCL pins feature integrated spike-suppression filters and Schmitt triggers to minimize the effects of input spikes and bus noise. The TMP75C-Q1 supports the transmission protocol for both fast (1 kHz to 400 kHz) and high-speed (1 kHz to 3 MHz) modes. All data bytes are transmitted MSB first.

7.3.3.1 Bus Overview

The device that initiates the transfer is called a *master*, and the devices controlled by the master are *slaves*. The bus must be controlled by a master device that generates the serial clock (SCL), controls the bus access, and generates the start and stop conditions.

To address a specific device, initiate a start condition by pulling the data line (SDA) from a high to a low logic level while SCL is high. All slaves on the bus shift in the slave address byte; the last bit indicates whether a read or write operation follows. During the ninth clock pulse, the slave being addressed responds to the master by generating an acknowledge bit and pulling SDA low.

Data transfer is then initiated and sent over eight clock pulses followed by an acknowledge bit. During data transfer, SDA must remain stable while SCL is high because any change in SDA while SCL is high is interpreted as a start or stop signal.

After all data have been transferred, the master generates a stop condition indicated by pulling SDA from low to high, while SCL is high.

7.3.3.2 Serial Bus Address

To communicate with the TMP75C-Q1, the master must first communicate with slave devices using a slave address byte. The slave address byte consists of seven address bits, and a direction bit indicating the intent of executing either a read or write operation. The TMP75C-Q1 features three address pins that allow up to eight devices to be addressed on a single bus. The TMP75C-Q1 latches the status of the address pins at the start of a communication. Table 2 describes the pin logic levels and the corresponding address values.

Table 2. Address Pin Connections and Slave Addresses

DEVICE TWO-WIRE ADDRESS	A2	A1	A0
1001000	GND	GND	GND
1001001	GND	GND	V_S
1001010	GND	V_S	GND
1001011	GND	V_S	V_S
1001100	V_S	GND	GND
1001101	V_S	GND	V_S
1001110	V_S	V_S	GND
1001111	V_S	V_S	V_S

7.3.3.3 Writing and Reading Operation

Accessing a particular register on the TMP75C-Q1 is accomplished by writing the appropriate value to the pointer register. The value for the pointer register is the first byte transferred after the slave address byte with the R/$\overline{W}$ bit low. Every write operation to the TMP75C-Q1 requires a value for the pointer register (see Figure 9).

When reading from the TMP75C-Q1, the last value stored in the pointer register by a write operation is used to determine which register is read by a read operation. To change the register pointer for a read operation, a new value must be written to the pointer register. This action is accomplished by issuing a slave address byte with the R/$\overline{W}$ bit low, followed by the pointer register byte. No additional data are required. The master can then generate a start condition and send the slave address byte with the R/$\overline{W}$ bit high to initiate the read command. See Figure 10 for details of this sequence. If repeated reads from the same register are desired, there is no need to continually send the pointer register bytes because the TMP75C-Q1 stores the pointer register value until it is changed by the next write operation.

Note that register bytes are sent with the most significant byte first, followed by the least significant byte.

7.3.3.4 Slave Mode Operations

The TMP75C-Q1 can operate as a slave receiver or slave transmitter.

7.3.3.4.1 Slave Receiver Mode:

The first byte transmitted by the master is the slave address, with the R/$\overline{W}$ bit low. The TMP75C-Q1 then acknowledges reception of a valid address. The next byte transmitted by the master is the pointer register. The TMP75C-Q1 then acknowledges reception of the pointer register byte. The next byte or bytes are written to the register addressed by the pointer register. The TMP75C-Q1 acknowledges reception of each data byte. The master can terminate data transfer by generating a start or stop condition.

7.3.3.4.2 Slave Transmitter Mode:

The first byte transmitted by the master is the slave address, with the R/$\overline{W}$ bit high. The slave acknowledges reception of a valid slave address. The next byte is transmitted by the slave and is the most significant byte of the register indicated by the pointer register. The master acknowledges reception of the data byte. The next byte transmitted by the slave is the least significant byte. The master acknowledges reception of the data byte. The master can terminate data transfer by generating a not-acknowledge bit on reception of any data byte, or by generating a start or stop condition.

7.3.3.5 High-Speed (Hs) Mode

In order for the two-wire bus to operate at frequencies above 400 kHz, the master device must issue an SMBus Hs-mode master code (00001xxx) as the first byte after a start condition to switch the bus to high-speed operation. The TMP75C-Q1 does not acknowledge this byte, but does switch its input filters on SDA and SCL and its output filters on SDA to operate in Hs-mode, allowing transfers at up to 3 MHz. After the Hs-mode master code has been issued, the master transmits a two-wire slave address to initiate a data-transfer operation. The bus continues to operate in Hs-mode until a stop condition occurs on the bus. Upon receiving the stop condition, the TMP75C-Q1 switches the input and output filters back to fast-mode operation.

7.3.3.6 Timeout Function

The TMP75C-Q1 resets the serial interface if SCL or SDA are held low for 22 ms (typ) between a start and stop condition. If the TMP75C-Q1 is pulled low, it releases the bus and then waits for a start condition. To avoid activating the timeout function, it is necessary to maintain a communication speed of at least 1 kHz for the SCL operating frequency.

7.3.3.7 Two-Wire Timing

The TMP75C-Q1 is two-wire and SMBus compatible. Figure 8 to Figure 10 describe the various operations on the TMP75C-Q1. Parameters for Figure 8 are defined in Table 3. Bus definitions are:

Bus Idle Both SDA and SCL lines remain high.

Start Data Transfer A change in the state of the SDA line, from high to low, while the SCL line is high defines a start condition. Each data transfer is initiated with a start condition.

Stop Data Transfer A change in the state of the SDA line from low to high while the SCL line is high defines a stop condition. Each data transfer is terminated with a repeated start or stop condition.

Data Transfer The number of data bytes transferred between a start and a stop condition is not limited, and is determined by the master device.

The receiver acknowledges the transfer of data. It is also possible to use the TMP75B for single-byte updates. To update only the MS byte, terminate communication by issuing a start or stop condition on the bus.

Acknowledge Each receiving device, when addressed, must generate an acknowledge bit.

A device that acknowledges must pull down the SDA line during the acknowledge clock pulse so that the SDA line is stable low during the high period of the acknowledge clock pulse. Setup and hold times must be taken into account. When a master receives data, the termination of the data transfer can be signaled by the master generating a *not-acknowledge* (1) on the last byte transmitted by the slave.

Table 3. Timing Diagram Requirements

			FAST MODE		HIGH-SPEED MODE		
			MIN	MAX	MIN	MAX	UNIT
$f_{(SCL)}$	SCL operating frequency	$V_S \geq 1.8$ V	0.001	0.4	0.001	3	MHz
		$V_S < 1.8$ V	0.001	0.4	0.001	2.5	MHz
$t_{(BUF)}$	Bus free time between stop and start conditions	$V_S \geq 1.8$ V	1300		160		ns
		$V_S < 1.8$ V	1300		260		ns
$t_{(HDSTA)}$	Hold time after repeated start condition. After this period, the first clock is generated.		600		160		ns
$t_{(SUSTA)}$	Repeated start condition setup time		600		160		ns
$t_{(SUSTO)}$	Stop condition setup time		600		160		ns
$t_{(HDDAT)}$	Data hold time	$V_S \geq 1.8$ V	0	900	0	100	ns
		$V_S < 1.8$ V	0	900	0	140	ns
$t_{(SUDAT)}$	Data setup time	$V_S \geq 1.8$ V	100		10		ns
		$V_S < 1.8$ V	100		20		ns
$t_{(LOW)}$	SCL clock low period	$V_S \geq 1.8$ V	1300		190		ns
		$V_S < 1.8$ V	1300		240		ns
$t_{(HIGH)}$	SCL clock high period		600		60		ns
$t_{R(SDA)}$, $t_{F(SDA)}$	Data rise and fall time			300		80	ns
$t_{R(SCL)}$, $t_{F(SCL)}$	Clock rise and fall time			300		40	ns
t_R	Clock and data rise time for SCLK ≤ 100 kHz			1000			ns

7.3.3.8 Two-Wire Timing Diagrams

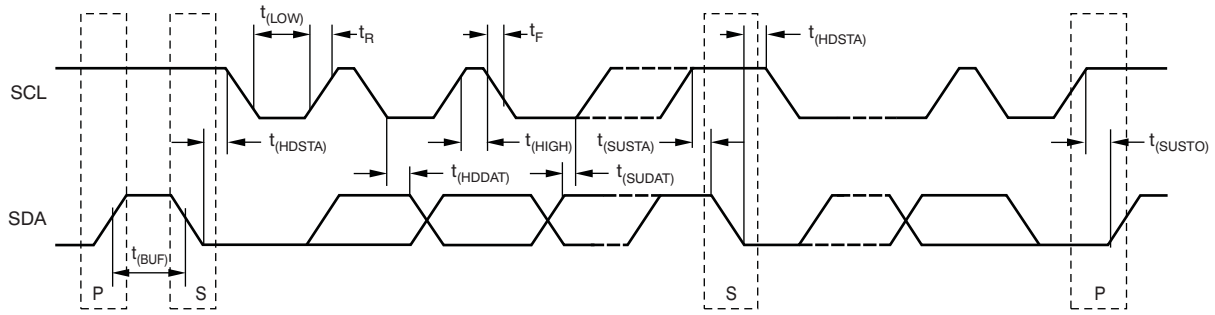
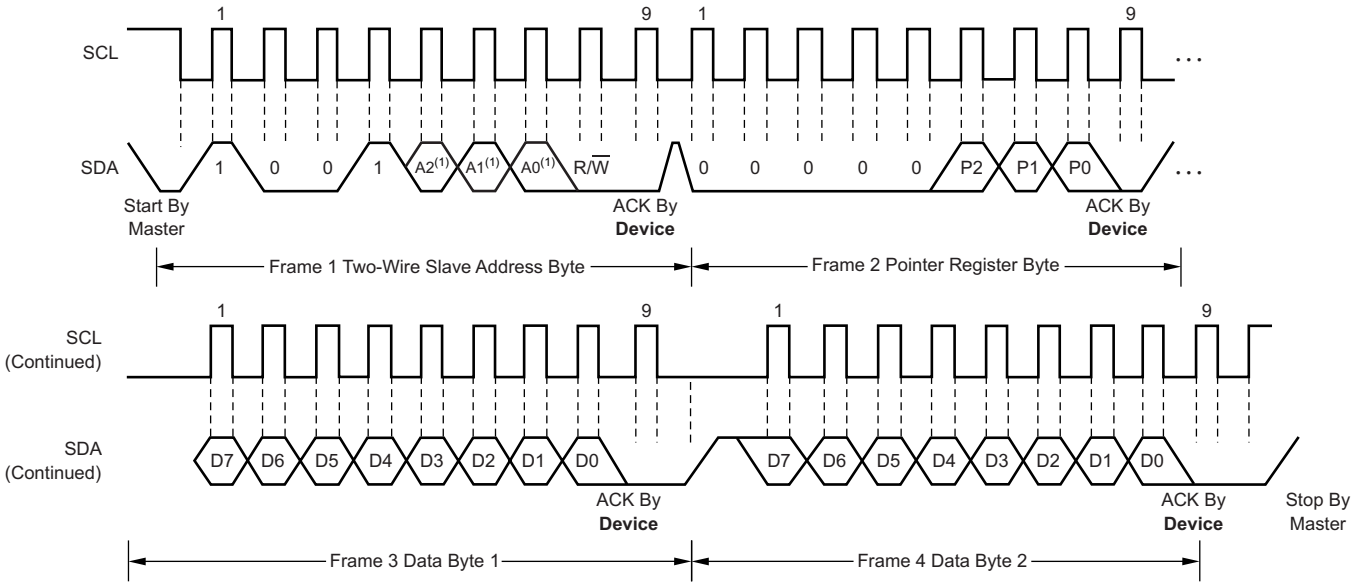
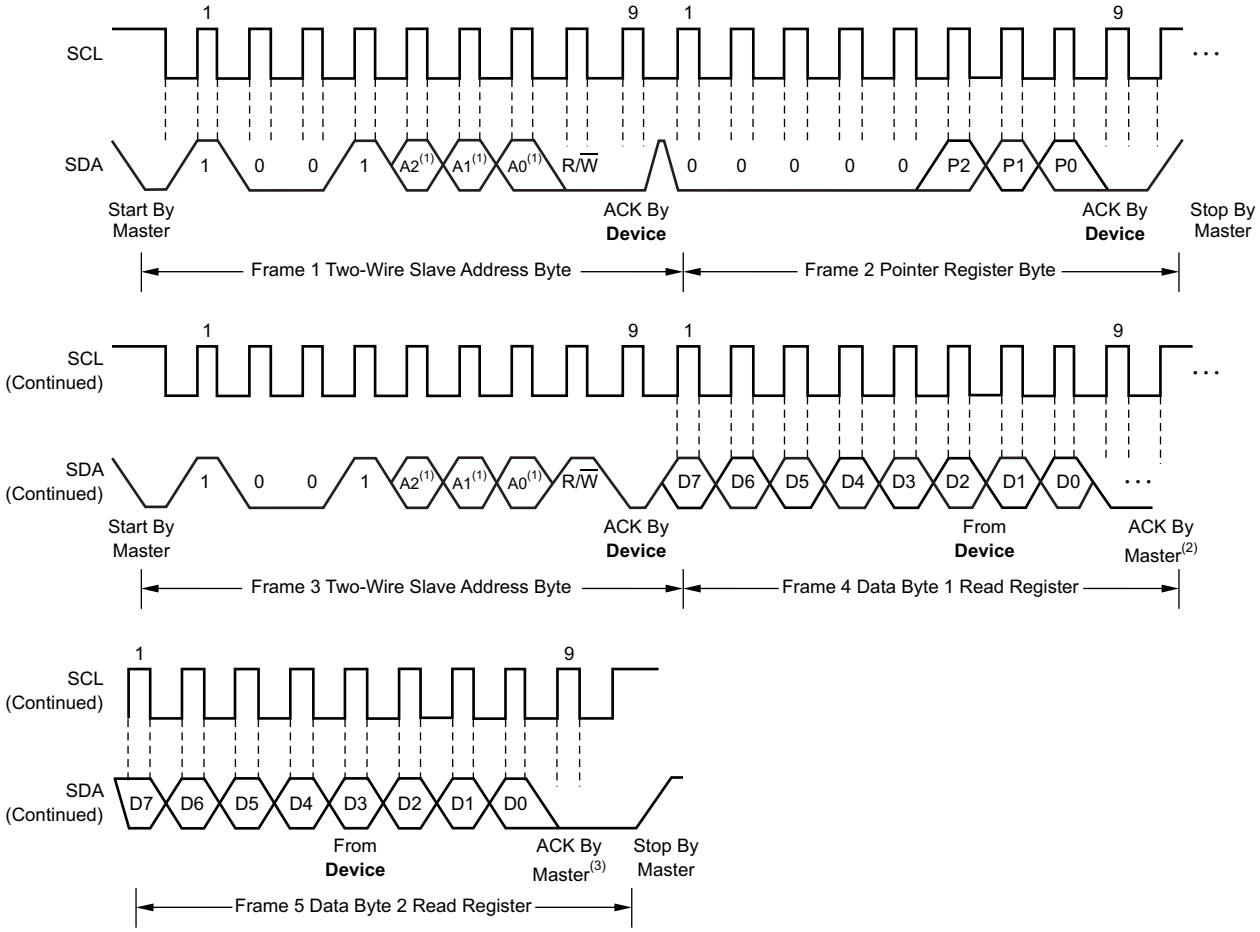


Figure 8. Two-Wire Timing Diagram



(1) The value of A0, A1, and A2 are determined by the connections of the corresponding pins.

Figure 9. Two-Wire Timing Diagram for Write Word Format



(1) The value of A0, A1, and A2 are determined by the connections of the corresponding pins.

(2) Master should leave SDA high to terminate a single-byte read operation.

(3) Master should leave SDA high to terminate a two-byte read operation.

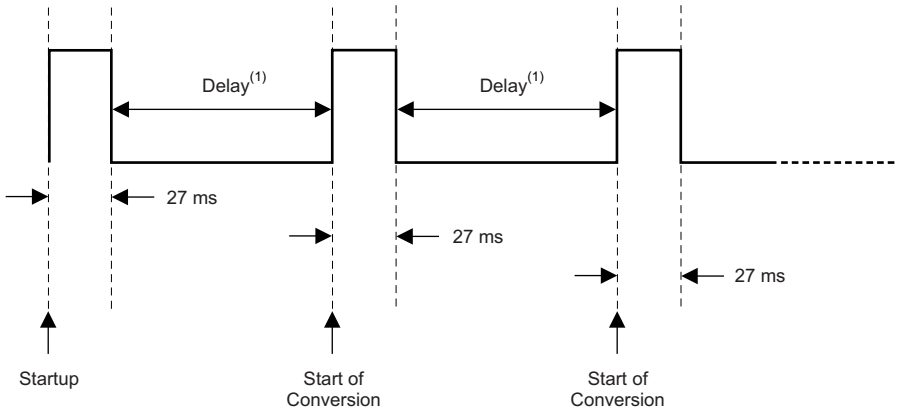
Figure 10. Two-Wire Timing Diagram for Read Word Format

7.4 Device Functional Modes

7.4.1 Continuous-Conversion Mode

The default mode of the TMP75C-Q1 is continuous conversion, where the ADC performs continuous temperature conversions and stores each result to the Temperature register, overwriting the result from the previous conversion. The typical conversion rate of TMP75C-Q1 is 12 Hz, with 80 ms between the start of each consecutive conversion. The TMP75C-Q1 has a typical conversion time of 27 ms. To achieve its conversion rates, the TMP75C-Q1 makes a conversion, and then powers down and waits for a delay 53 ms.

After power-up, the TMP75C-Q1 immediately starts a conversion, as shown in Figure 11. The first result is available after 27 ms (typical). The active quiescent current during conversion is 45 μA (typical at +25°C). The quiescent current during delay is 1 μA (typical at +25°C).



(1) Delay is set to 53 ms (typ).

Figure 11. Conversion Start

7.4.2 Shutdown Mode

The shutdown mode saves maximum power by shutting down all device circuitry other than the serial interface, and reduces current consumption to typically less than 0.3 μA. Shutdown mode is enabled when the SD bit in the configuration register is set to 1; the device shuts down and terminates a conversion if it is ongoing. When SD is equal to 0, the device operates in continuous-conversion mode. When shutdown mode is enabled, the ALERT pin and fault counter clear in both comparator and interrupt modes. The ALERT pin and the fault counter remain clear until the SD bit is set.

7.4.3 One-Shot Mode

The TMP75C-Q1 features a one-shot temperature measurement mode. When the device is in continuous conversion (SD = 0), writing a 1 to the OS bit enables shutdown mode, where any write to the one-shot register triggers a single temperature conversion. The device returns to the shutdown state at the completion of the single conversion, and a subsequent write to the one-shot register triggers another single conversion followed by a return to shutdown state. This mode reduces power consumption in the TMP75C-Q1 when continuous temperature monitoring is not required.

When the device is in complete shutdown (SD = 1), the one-shot mode is not active regardless of the state of the OS bit, and a write to the one-shot register has no effect.

7.5 Programming

Figure 12 shows the internal register structure of the TMP75C-Q1. Use the 8-bit pointer register to address a given data register. The pointer register uses the three LSBs to identify which of the data registers respond to a read or write command. Figure 13 identifies the bits of the pointer register byte.

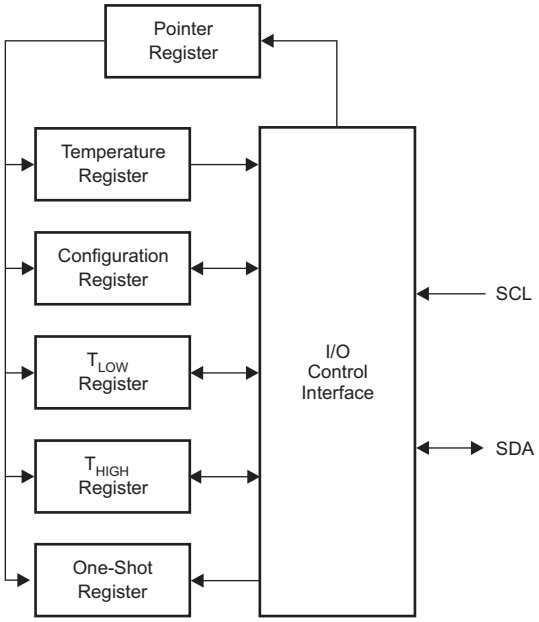


Figure 12. Internal Register Structure

7.6 Register Map

Table 4 describes the registers available in the TMP75C-Q1 with their pointer addresses, followed by the description of the bits in each register.

Table 4. Register Map and Pointer Addresses

P2	P1	P0	REGISTER
0	0	0	Temperature register (read only, default)
0	0	1	Configuration register (read/write)
0	1	0	T_{LOW} register (read/write)
0	1	1	T_{HIGH} register (read/write)
1	0	0	One-Shot register (write only; write any value to start a conversion)

Figure 13. Pointer Register (pointer = N/A) [reset = 00h]

7	6	5	4	3	2	1	0
Reserved					P2	P1	P0
W-0h					W-0h	W-0h	W-0h

LEGEND: R/W = Read/Write; R = Read only; W = Write only; -n = value after reset

Figure 14. Temperature Register (pointer = 0h) [reset = 0000h]

15	14	13	12	11	10	9	8
T11	T10	T9	T8	T7	T6	T5	T4
R-00h							
7	6	5	4	3	2	1	0
T3	T2	T1	T0	Reserved			
R-0h				R-0h			

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 5. Temperature Register Description

Name	Description
T11 to T4	The 8 MSBs of the temperature result (resolution of 1°C)
T3 to T0	The 4 LSBs of the temperature result (resolution of 0.0625°C)

Figure 15. Configuration Register (pointer = 1h) [reset = 0000h]

15	14	13	12	11	10	9	8
Reserved		OS	FQ		POL	TM	SD
R/W-0h		R/W-0h	R/W-0h		R/W-0h	R/W-0h	R/W-0h
7	6	5	4	3	2	1	0
Reserved							
R-00h							

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 6. Configuration Register Description

Name	Description
Reserved	Reserved bits Write 0 to these bits on configuration register update.
OS	One-shot control SD = 0 and OS = 0: Continuous conversion mode (default) SD = 0 and OS = 1: One-shot mode; the device is in shutdown mode but writing any value to the one-shot register initiates a conversion. The device returns to shutdown mode at the end of the conversion. SD = 1 and OS = x: The device is in shutdown mode and the status of the OS bit has no effect. Writing to the one-shot register does not start a conversion.
FQ	Fault queue to trigger the ALERT pin FQ = 0h: 1 fault (default) FQ = 1h: 2 faults FQ = 2h: 4 faults FQ = 3h: 6 faults
POL	ALERT polarity control POL = 0: ALERT is active low (default) POL = 1: ALERT is active high
TM	ALERT thermostat mode control TM = 0: ALERT is in comparator mode (default) TM = 1: ALERT is in interrupt mode
SD	Shutdown control bit SD = 0: Device is in continuous conversion mode (default) SD = 1: Device is in shutdown mode

Figure 16. T_{LOW} - Temperature Low Limit Register (pointer = 2h) [reset = 4B00h](1)

15	14	13	12	11	10	9	8
L11	L10	L9	L8	L7	L6	L5	L4
R/W-4Bh							
7	6	5	4	3	2	1	0
L3	L2	L1	L0	Reserved			
R/W-0h				R-0h			

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

(1) 4B00h = 75°C.

Table 7. T_{LOW} Register Description

Name	Description
L11 to L4	The 8 MSBs of the temperature low limit (resolution of 1°C)
L3 to L0	The 4 LSBs of the temperature low limit (resolution of 0.0625°C)

Figure 17. T_{HIGH} - Temperature High Limit Register (pointer = 3h) [reset = 5000h](1)

15	14	13	12	11	10	9	8
H11	H10	H9	H8	H7	H6	H5	H4
R/W-50h							
7	6	5	4	3	2	1	0
H3	H2	H1	H0	Reserved			
R/W-0h				R-0h			

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

(1) 5000h = 80°C.

Table 8. T_{HIGH} Register Description

Name	Description
H11 to H4	The 8 MSBs of the temperature high limit (resolution of 1°C)
H3 to H0	The 4 LSBs of the temperature high limit (resolution of 0.0625°C)

8 Application and Implementation

8.1 Application Information

The TMP75C-Q1 is used to measure the PCB temperature of the location it is mounted. The programmable address options allow up to eight locations on the board to be monitored on a single serial bus. Connecting the ALERT pins together and programming the temperature limit registers to desired values allows for a temperature watchdog operation of all devices, interrupting the host controller only if the temperature exceeds the limits.

8.2 Typical Application

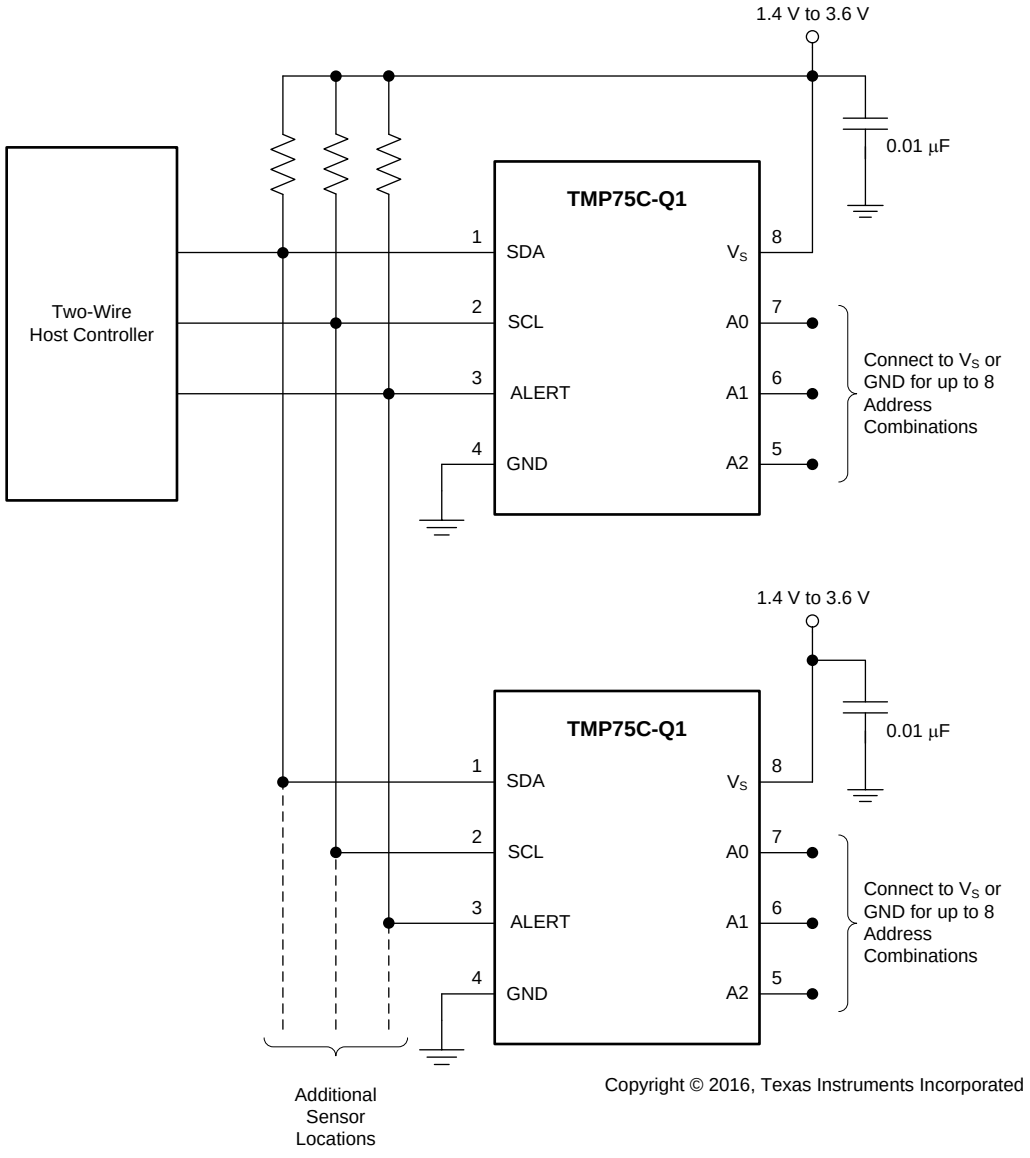


Figure 18. Temperature Monitoring of Multiple Locations on a PCB

Typical Application (continued)

8.2.1 Design Requirements

The TMP75C-Q1 only requires pull-up resistors on SDA and ALERT, although a pull-up resistor is typically present on the SCL as well. A 0.01-μF bypass capacitor on the supply is recommended, as shown in Figure 18. The SCL, SDA, and ALERT lines can be pulled up to a supply that is equal to or higher than V_S through the pull-up resistors. To configure one of eight different addresses on the bus, connect A0, A1, and A2 to either V_S or GND.

8.2.2 Detailed Design Procedure

The TMP75C-Q1 should be placed in close proximity to the heat source to be monitored, with a proper layout for good thermal coupling. This ensures that temperature changes are captured within the shortest possible time interval.

8.2.3 Application Curves

Figure 19 shows the step response of the TMP75C-Q1 to a submersion in an oil bath of 100°C from room temperature (27°C). The time-constant, or the time for the output to reach 63% of the input step, is 1.5 seconds.

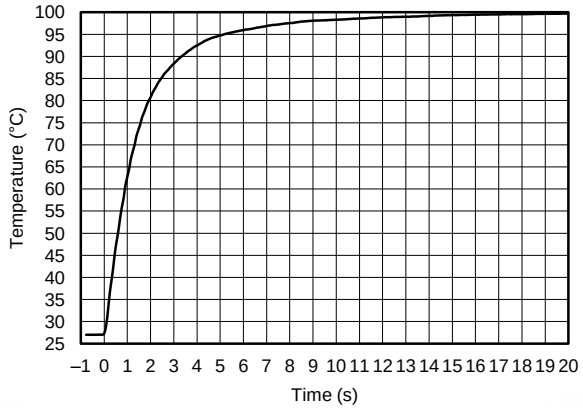


Figure 19. Temperature Step Response

9 Power Supply Recommendations

The TMP75C-Q1 operates with a power supply in the range of 1.4 V to 3.6 V. It is optimized for operation at 1.8-V supply but can measure temperature accurately in the full supply range.

A power-supply bypass capacitor is required for stability; place this capacitor as close as possible to the supply and ground pins of the device. A typical value for this supply bypass capacitor is 0.01 μF. Applications with noisy or high-impedance power supplies may require additional decoupling capacitors to reject power-supply noise.

10 Layout

10.1 Layout Guidelines

Place the power-supply bypass capacitor as close as possible to the supply and ground pins. The recommended value of this bypass capacitor is 0.01 μF. Additional decoupling capacitance can be added to compensate for noisy or high-impedance power supplies.

Pull up the open-drain output pins (SDA and ALERT) to a supply voltage rail (V_S or higher but up to 3.6 V) through 10-kΩ pull-up resistors.

10.2 Layout Example

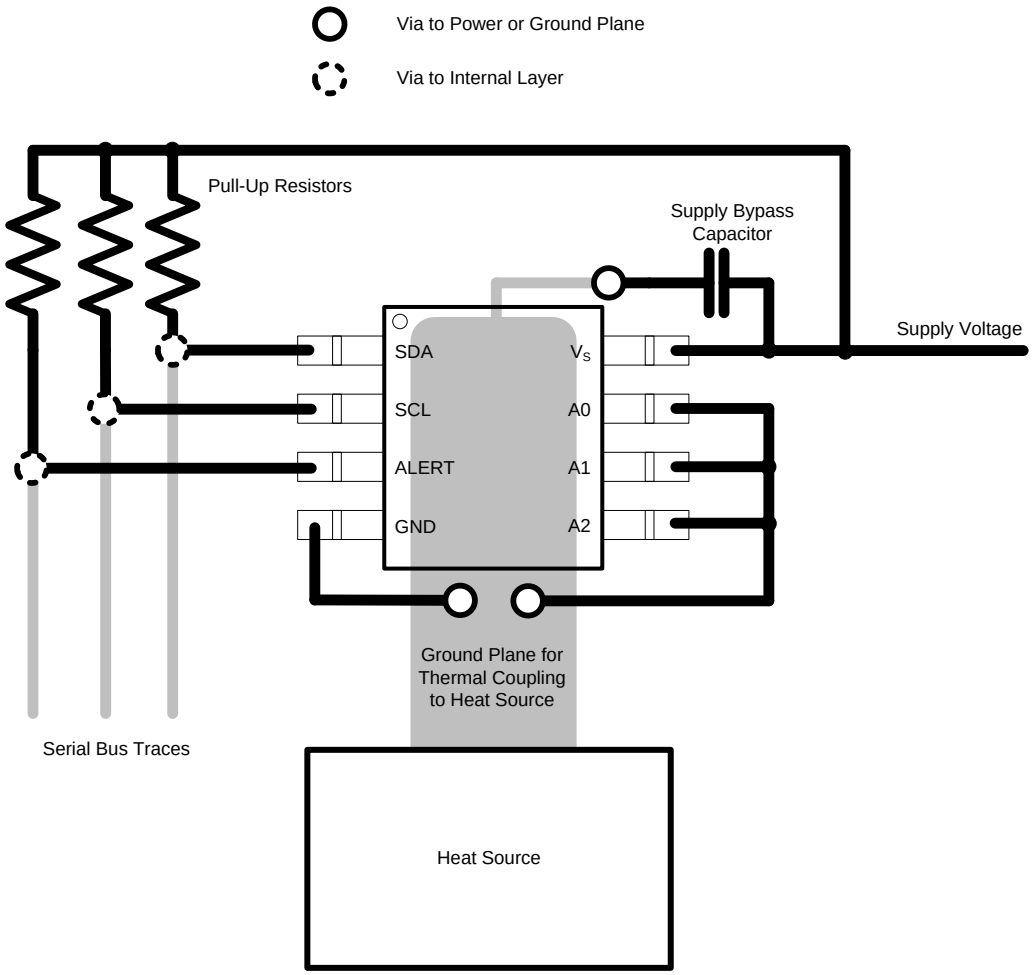


Figure 20. Layout Example

11 デバイスおよびドキュメントのサポート

11.1 ドキュメントのサポート

11.1.1 関連資料

関連資料については、以下を参照してください。

『TMP75BEVMおよびTMP75CEVMユーザー・ガイド』(SBOU141)

11.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.comのデバイス製品フォルダを開いてください。右上の隅にある「*通知を受け取る*」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

11.3 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™オンライン・コミュニティ ***TIのE2E (Engineer-to-Engineer) コミュニティ。エンジニア間の共同作業を促進するために開設されたものです。e2e.ti.comでは、他のエンジニアに質問し、知識を共有し、アイディアを検討して、問題解決に役立てることができます。***

設計サポート ***TIの設計サポート*** **役に立つE2Eフォーラムや、設計サポート・ツールをすばやく見つけることができます。技術サポート用の連絡先情報も参照できます。**

11.4 商標

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

11.5 静電気放電に関する注意事項

すべての集積回路は、適切なESD保護方法を用いて、取扱いと保存を行うようにして下さい。

静電気放電はわずかな性能の低下から完全なデバイスの故障に至るまで、様々な損傷を与えます。高精度の集積回路は、損傷に対して敏感であり、極めてわずかなパラメータの変化により、デバイスに規定された仕様に適合しなくなる場合があります。

11.6 用語集

SLYZ022 — *TI用語集*.

この用語集には、用語や略語の一覧および定義が記載されています。

12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMP75CQDGKRQ1	Active	Production	VSSOP (DGK) | 8	2500 | LARGE T&R	Yes	NIPDAU | NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	T75CQ
TMP75CQDGKRQ1.B	Active	Production	VSSOP (DGK) | 8	2500 | LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	T75CQ
TMP75CQDRQ1	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	T75CQ
TMP75CQDRQ1.B	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	T75CQ

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

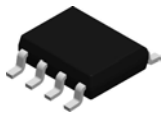
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF TMP75C-Q1 :

- Catalog : TMP75C

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

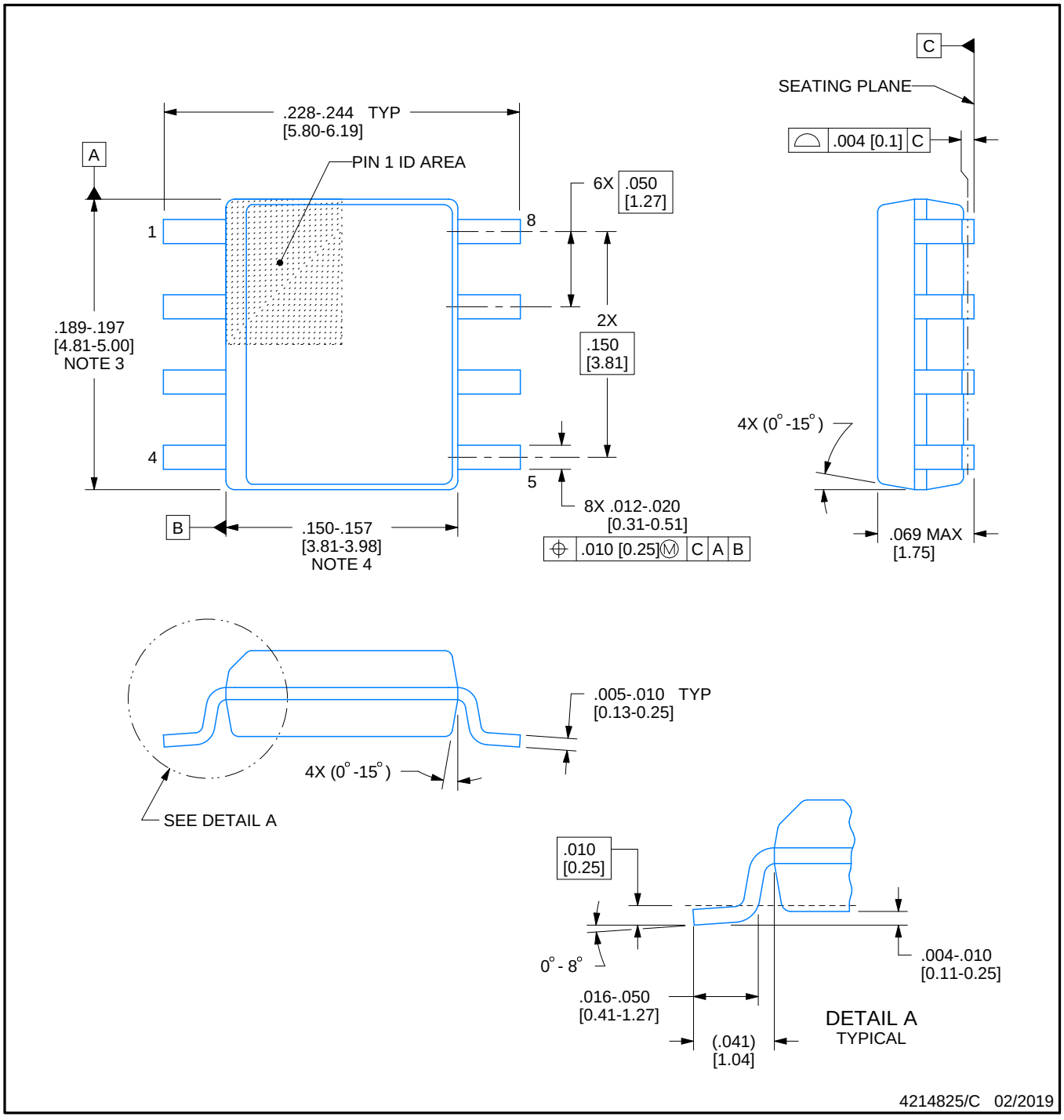


PACKAGE OUTLINE

D0008A

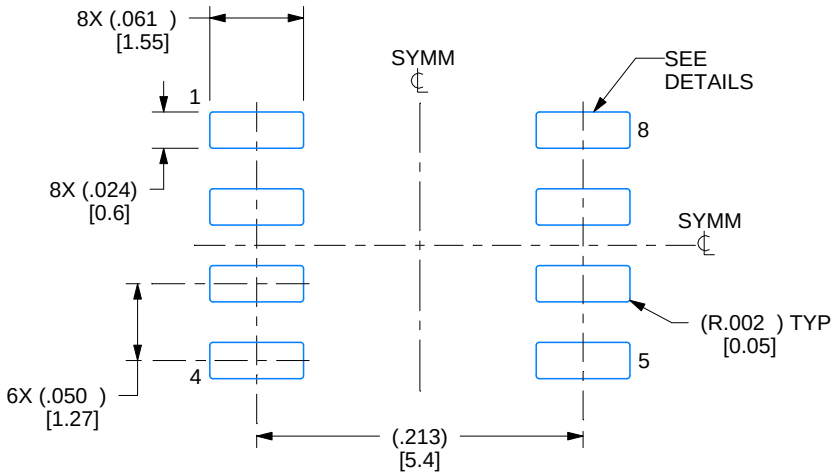
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

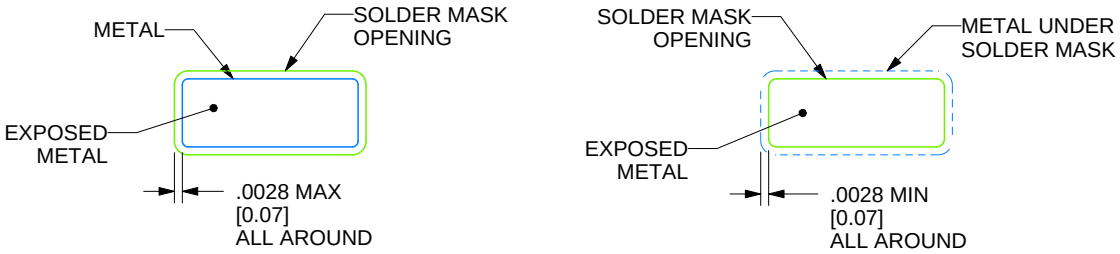


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

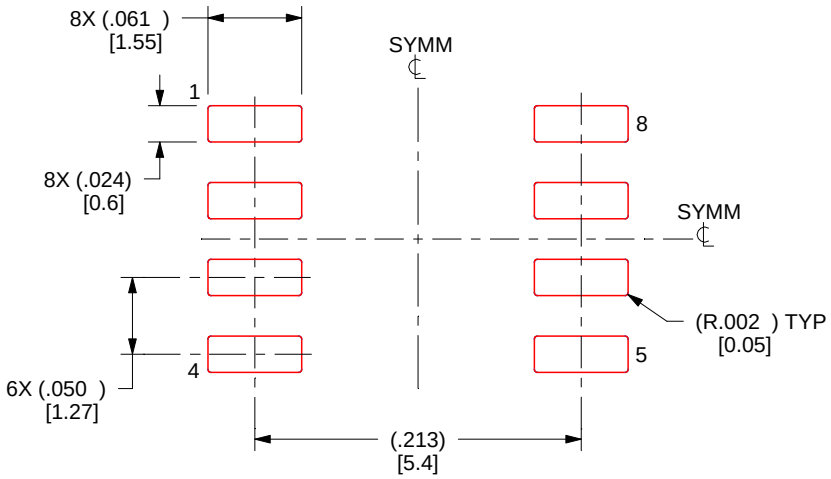
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

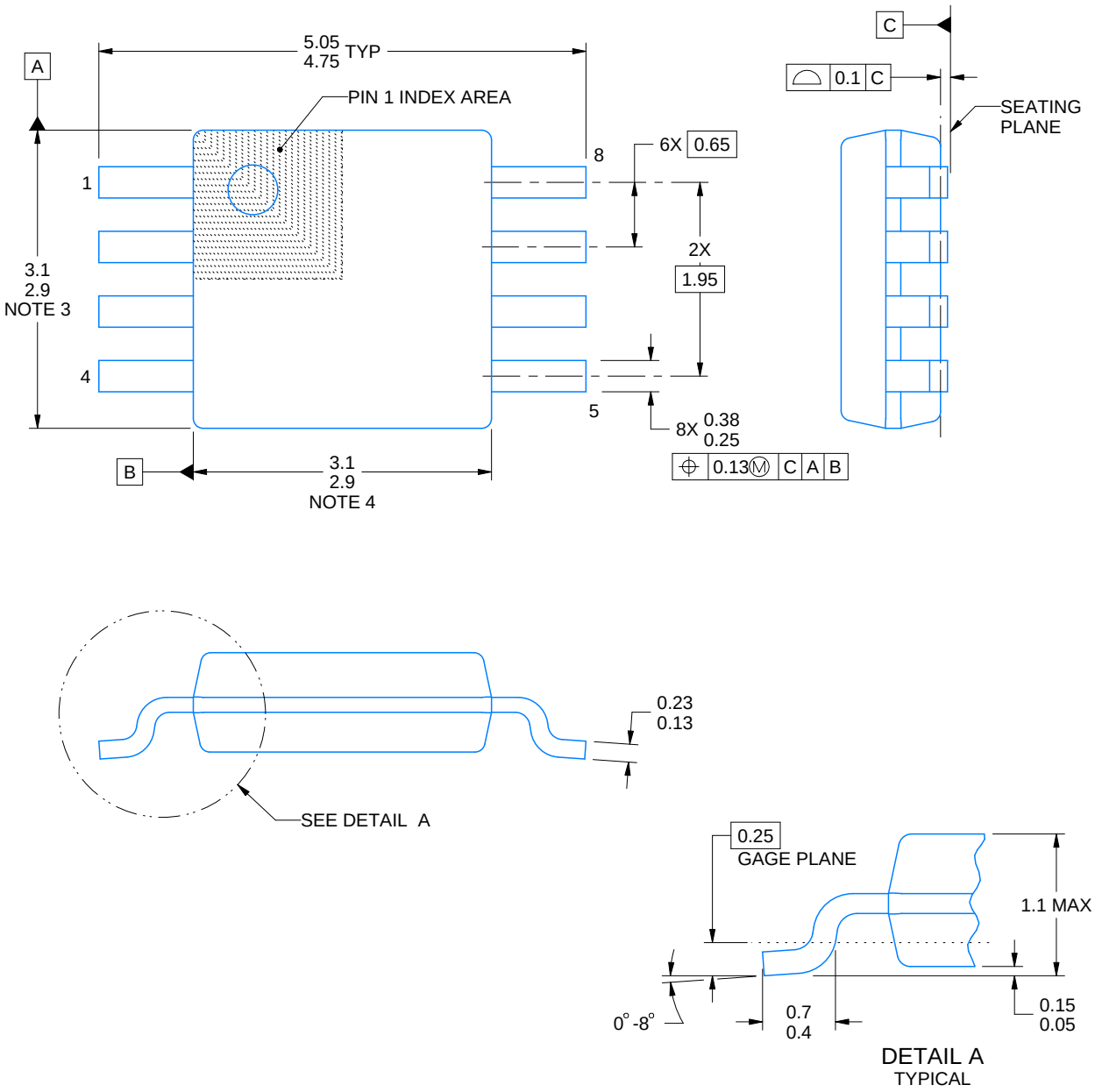
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DGK0008A

VSSOP - 1.1 mm max height

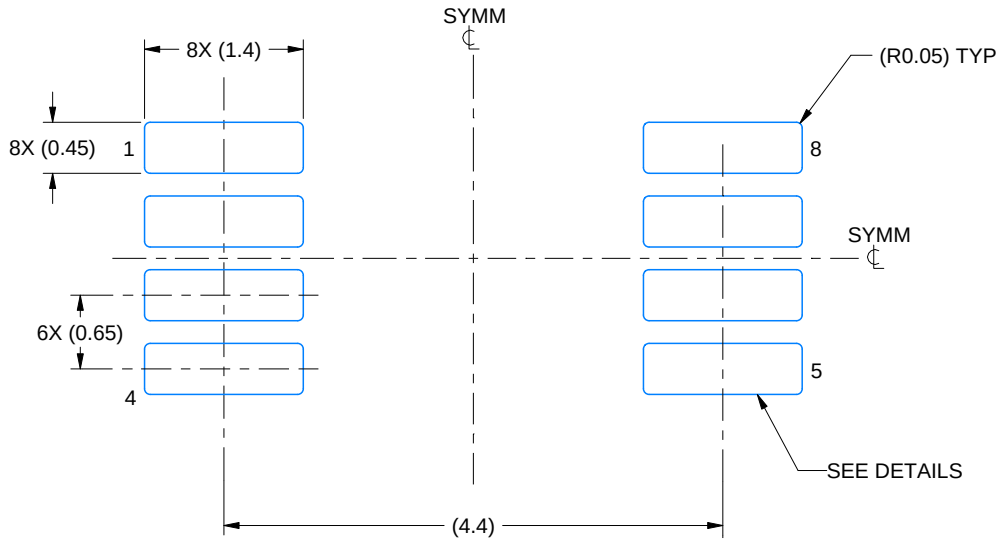
SMALL OUTLINE PACKAGE



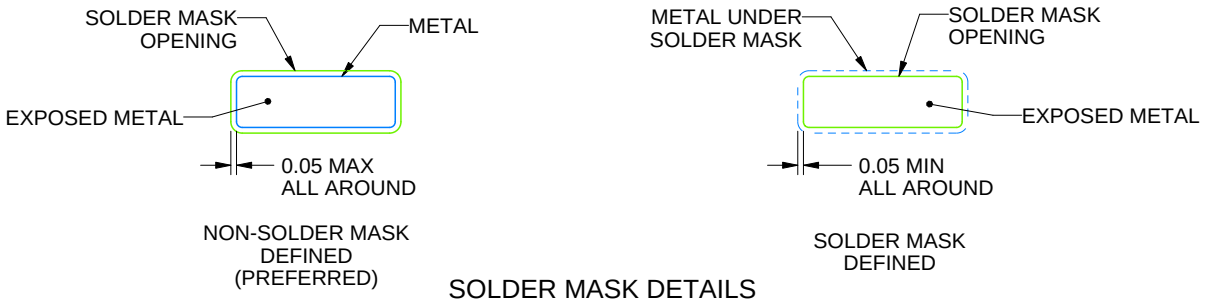
PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X

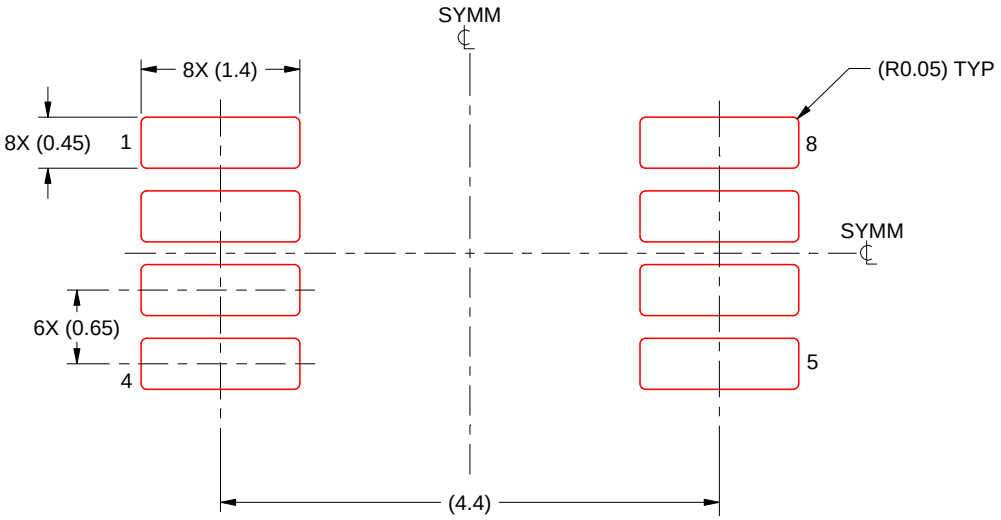


SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.



SOLDER PASTE EXAMPLE
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

重要なお知らせと免責事項

TI は、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、TI 製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した TI 製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとします。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている TI 製品を使用するアプリケーションの開発の目的でのみ、TI はその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。TI や第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、TI およびその代理人を完全に補償するものとし、TI は一切の責任を拒否します。

TI の製品は、 TI の販売条件 、 TI の総合的な品質ガイドライン 、 ti.com または TI 製品などに関連して提供される他の適用条件に従い提供されます。TI がこれらのリソースを提供することは、適用される TI の保証または他の保証の放棄の拡大や変更を意味するものではありません。 TI がカスタム、またはカスタマー仕様として明示的に指定していない限り、TI の製品は標準的なカタログに掲載される汎用機器です。

お客様がいかなる追加条項または代替条項を提案する場合も、TI はそれらに異議を唱え、拒否します。

最終更新日：2025 年 10 月